

# Silicon Carbide (SiC) MOSFET – EliteSiC, 65 mohm, 1200 V, M3S, D2PAK-7L NTBG070N120M3S

## Features

- Typ.  $R_{DS(on)} = 65 \text{ m}\Omega @ V_{GS} = 18 \text{ V}$
- Ultra Low Gate Charge ( $Q_{G(tot)} = 57 \text{ nC}$ )
- High Speed Switching with Low Capacitance ( $C_{oss} = 57 \text{ pF}$ )
- 100% Avalanche Tested
- This Device is Halide Free and RoHS Compliant with exemption 7a, Pb-Free 2LI (on second level interconnection)

## Typical Applications

- Solar Inverters
- Electric Vehicle Charging Stations
- UPS (Uninterruptible Power Supplies)
- Energy Storage Systems
- SMPS (Switch Mode Power Supplies)

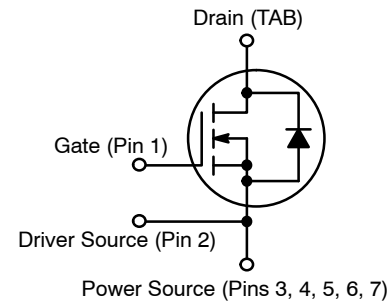
## MAXIMUM RATINGS ( $T_J = 25^\circ\text{C}$ unless otherwise noted)

Parameter			Symbol	Value	Unit
Drain-to-Source Voltage			V <sub>DSS</sub>	1200	V
Gate-to-Source Voltage			V <sub>GS</sub>	-10/+22	V
Continuous Drain Current (Notes 2, 3)	Steady State	T <sub>C</sub> = 25°C	I <sub>D</sub>	36	A
Power Dissipation (Note 2)			P <sub>D</sub>	172	W
Continuous Drain Current (Notes 2, 3)	Steady State	T <sub>C</sub> = 100°C	I <sub>D</sub>	25	A
Power Dissipation (Note 2)			P <sub>D</sub>	86	W
Pulsed Drain Current (Note 4)	T <sub>C</sub> = 25°C		I <sub>DM</sub>	93	A
Operating Junction and Storage Temperature Range			T <sub>J</sub> , T <sub>stg</sub>	-55 to +175	°C
Source Current (Body Diode) T <sub>C</sub> = 25°C, V <sub>GS</sub> = -3 V (Note 2)			I <sub>S</sub>	33	A
Single Pulse Drain-to-Source Avalanche Energy (I <sub>L(pk)</sub> = 13.5 A, L = 1 mH) (Note 5)			E <sub>AS</sub>	91	mJ
Maximum Temperature for Soldering (10 s)			T <sub>L</sub>	270	°C

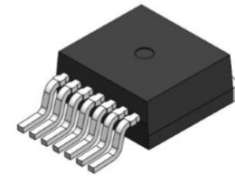
Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Surface mounted on a FR-4 board using 1 in<sup>2</sup> pad of 2 oz copper.
2. The entire application environment impacts the thermal resistance values shown, they are not constants and are only valid for the particular conditions noted.
3. The maximum current rating is based on typical  $R_{DS(on)}$  performance.
4. Repetitive rating, limited by max junction temperature.
5.  $E_{AS}$  of 91 mJ is based on starting  $T_J = 25^\circ\text{C}$ ;  $L = 1 \text{ mH}$ ,  $I_{AS} = 13.5 \text{ A}$ ,  $V_{DD} = 100 \text{ V}$ ,  $V_{GS} = 18 \text{ V}$ .

$V_{(BR)DSS}$	$R_{DS(on)} \text{ MAX}$	$I_D \text{ MAX}$
1200 V	87 m $\Omega$ @ 18 V	36 A

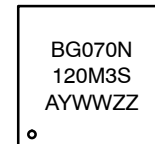


N-CHANNEL MOSFET



D2PAK-7L  
CASE 418BJ

## MARKING DIAGRAM



BG070N120M3S = Specific Device Code  
A = Assembly Location  
Y = Year  
WW = Work Week  
ZZ = Lot Traceability

## ORDERING INFORMATION

Device	Package	Shipping <sup>†</sup>
NTBG070N120M3S	D2PAK-7L	800 / Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

# NTBG070N120M3S

## THERMAL CHARACTERISTICS

Parameter	Symbol	Max	Unit
Junction-to-Case – Steady State (Note 2)	$R_{\theta JC}$	0.87	°C/W
Junction-to-Ambient – Steady State (Notes 1, 2)	$R_{\theta JA}$	40	

## RECOMMENDED OPERATING CONDITIONS

Parameter	Symbol	Value	Unit
Operation Values of Gate-to-Source Voltage	$V_{GSop}$	-5...-3 +18	V

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

## ELECTRICAL CHARACTERISTICS ( $T_J = 25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
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### OFF-STATE CHARACTERISTICS

Drain-to-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0\text{ V}, I_D = 1\text{ mA}$	1200	–	–	V
Drain-to-Source Breakdown Voltage Temperature Coefficient	$V_{(BR)DSS}/T_J$	$I_D = 1\text{ mA}$ , referenced to $25^\circ\text{C}$ (Note 7)	–	0.3	–	V/°C
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{GS} = 0\text{ V}, V_{DS} = 1200\text{ V}$	–	–	100	$\mu\text{A}$
Gate-to-Source Leakage Current	$I_{GSS}$	$V_{GS} = +22/-10\text{ V}, V_{DS} = 0\text{ V}$	–	–	$\pm 1$	$\mu\text{A}$

### ON-STATE CHARACTERISTICS

Gate Threshold Voltage	$V_{GS(TH)}$	$V_{GS} = V_{DS}, I_D = 7\text{ mA}$	2.04	2.9	4.4	V
Drain-to-Source On Resistance	$R_{DS(on)}$	$V_{GS} = 18\text{ V}, I_D = 15\text{ A}, T_J = 25^\circ\text{C}$	–	65	87	$\text{m}\Omega$
		$V_{GS} = 18\text{ V}, I_D = 15\text{ A}, T_J = 175^\circ\text{C}$ (Note 7)	–	136	–	
Forward Transconductance	$g_{FS}$	$V_{DS} = 10\text{ V}, I_D = 15\text{ A}$ (Note 7)	–	12	–	S

### CHARGES, CAPACITANCES & GATE RESISTANCE

Input Capacitance	$C_{ISS}$	$V_{GS} = 0\text{ V}, f = 1\text{ MHz}, V_{DS} = 800\text{ V}$	–	1230	–	$\text{pF}$
Output Capacitance	$C_{OSS}$		–	57	–	
Reverse Transfer Capacitance	$C_{RSS}$		–	5	–	
Total Gate Charge	$Q_{G(TOT)}$	$V_{GS} = -3/18\text{ V}, V_{DS} = 800\text{ V}, I_D = 15\text{ A}$	–	57	–	$\text{nC}$
Threshold Gate Charge	$Q_{G(TH)}$		–	3.2	–	
Gate-to-Source Charge	$Q_{GS}$		–	9.6	–	
Gate-to-Drain Charge	$Q_{GD}$		–	17	–	
Gate-Resistance	$R_G$	$f = 1\text{ MHz}$	–	4.2	–	$\Omega$

### SWITCHING CHARACTERISTICS

Turn-On Delay Time	$t_{d(ON)}$	$V_{GS} = -3/18\text{ V}, V_{DS} = 800\text{ V}, I_D = 15\text{ A}, R_G = 4.7\text{ }\Omega$ inductive load (Notes 6, 7)	–	11	–	$\text{ns}$
Rise Time	$t_r$		–	12	–	
Turn-Off Delay Time	$t_{d(OFF)}$		–	30	–	
Fall Time	$t_f$		–	8.8	–	
Turn-On Switching Loss	$E_{ON}$		–	119	–	$\mu\text{J}$
Turn-Off Switching Loss	$E_{OFF}$		–	36	–	
Total Switching Loss	$E_{tot}$		–	155	–	

# NTBG070N120M3S

## ELECTRICAL CHARACTERISTICS ( $T_J = 25^\circ\text{C}$ unless otherwise specified) (continued)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
<b>SOURCE-DRAIN DIODE CHARACTERISTICS</b>						
Continuous Source-Drain Diode Forward Current (Note 2)	$I_{SD}$	$V_{GS} = -3\text{ V}, T_C = 25^\circ\text{C}$ (Note 7)	–	–	33	A
Pulsed Source-Drain Diode Forward Current (Note 4)	$I_{SDM}$		–	–	93	
Forward Diode Voltage	$V_{SD}$	$V_{GS} = -3\text{ V}, I_{SD} = 15\text{ A}, T_J = 25^\circ\text{C}$	–	4.7	–	V
Reverse Recovery Time	$t_{RR}$	$V_{GS} = -3/18\text{ V}, I_{SD} = 15\text{ A},$ $dI_S/dt = 1000\text{ A}/\mu\text{s}, V_{DS} = 800\text{ V}$ (Note 7)	–	15	–	ns
Reverse Recovery Charge	$Q_{RR}$		–	63	–	nC
Reverse Recovery Energy	$E_{REC}$		–	5.7	–	$\mu\text{J}$
Peak Reverse Recovery Current	$I_{RRM}$		–	8.6	–	A
Charge time	$t_A$		–	8.3	–	ns
Discharge time	$t_B$		–	6.3	–	ns

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

6.  $E_{ON}/E_{OFF}$  result is with body diode

7. Defined by design, not subject to production test.

TYPICAL CHARACTERISTICS

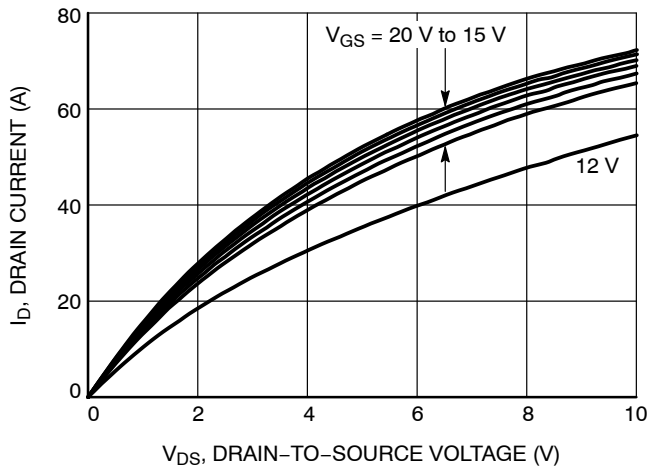


Figure 1. On-Region Characteristics

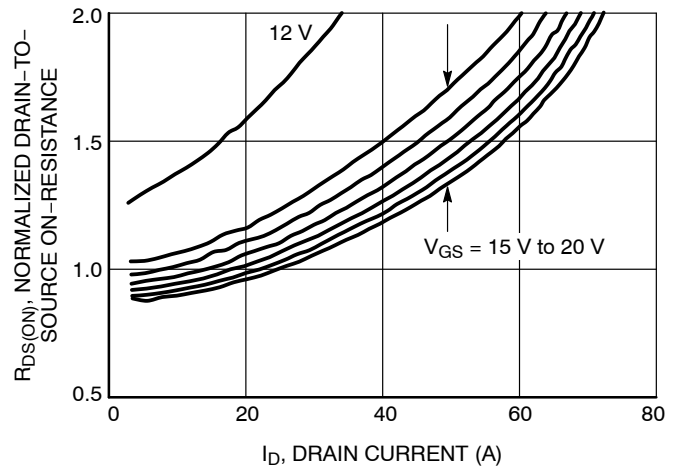


Figure 2. Normalized On-Resistance vs. Drain Current and Gate Voltage

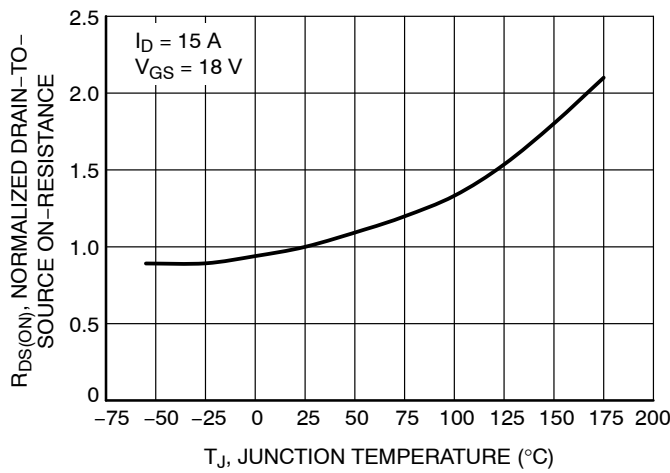


Figure 3. On-Resistance Variation with Temperature

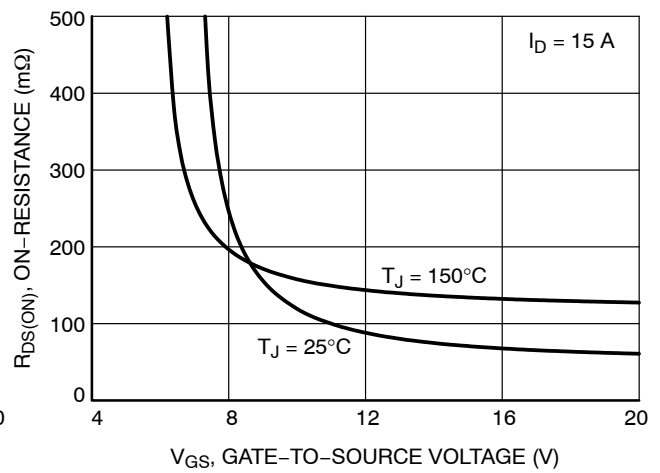


Figure 4. On-Resistance vs. Gate-to-Source Voltage

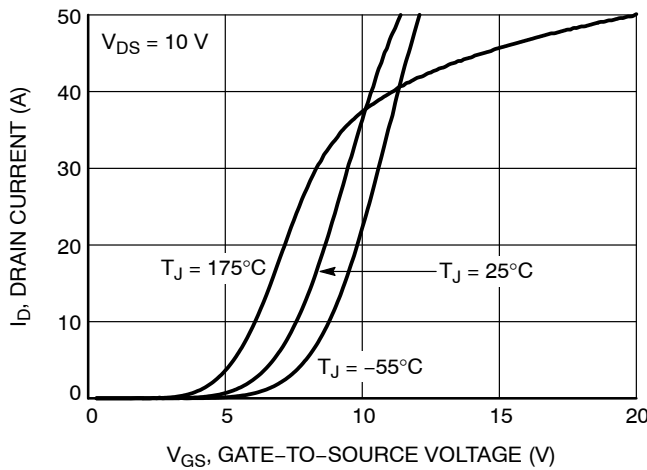


Figure 5. Transfer Characteristics

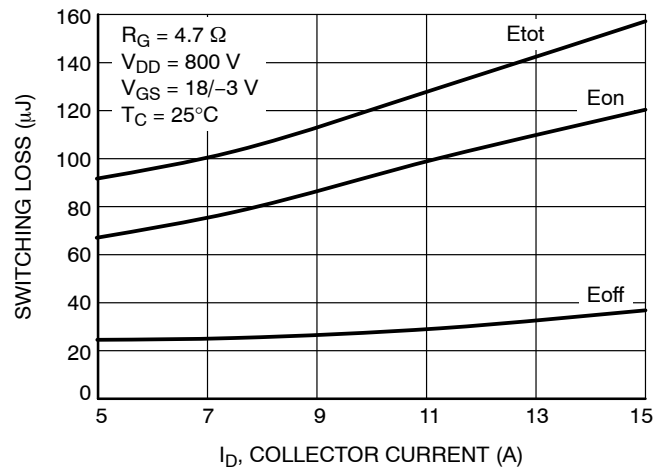


Figure 6. Switching Loss vs. Collector Current

TYPICAL CHARACTERISTICS

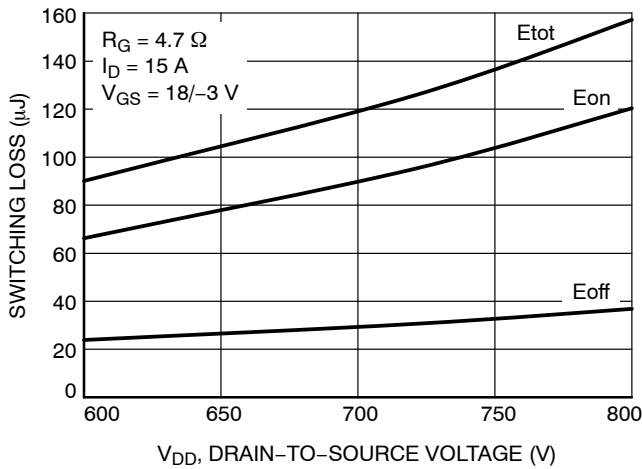


Figure 7. Switching Loss vs. Drain-to-Source Voltage

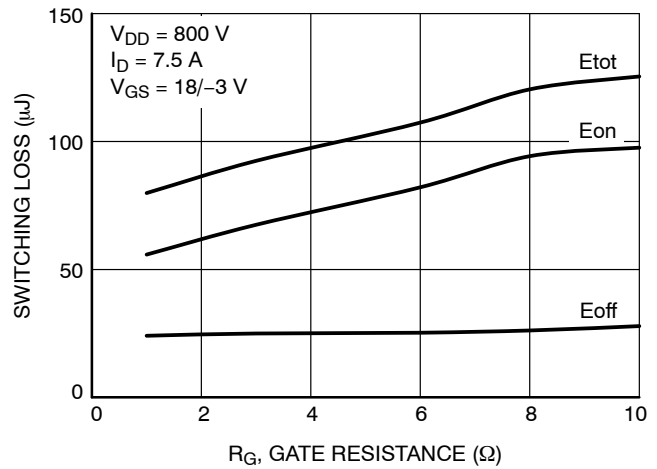


Figure 8. Switching Loss vs. Gate Resistance

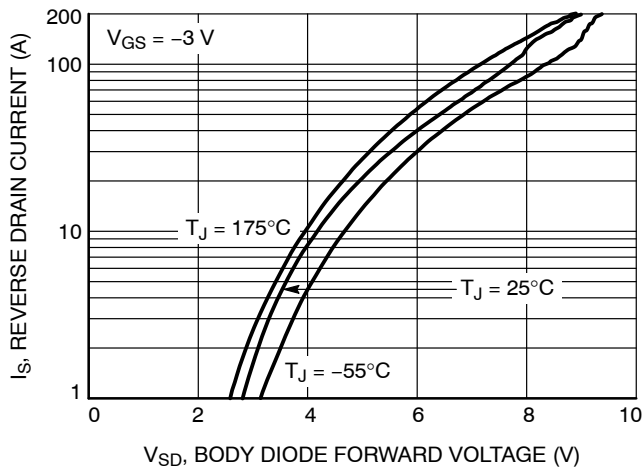


Figure 9. Reverse Drain Current vs. Body Diode Forward Voltage

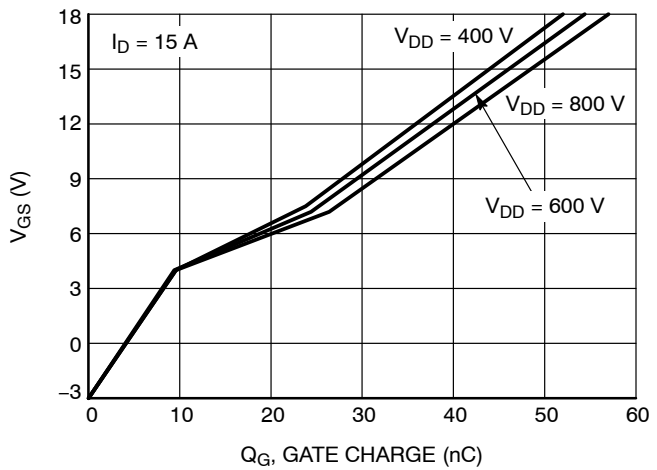


Figure 10. Gate-to-Source Voltage vs. Total Charge

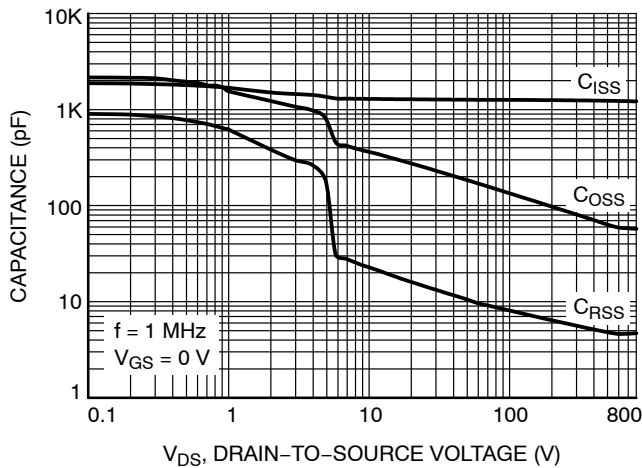


Figure 11. Capacitance vs. Drain-to-Source Voltage

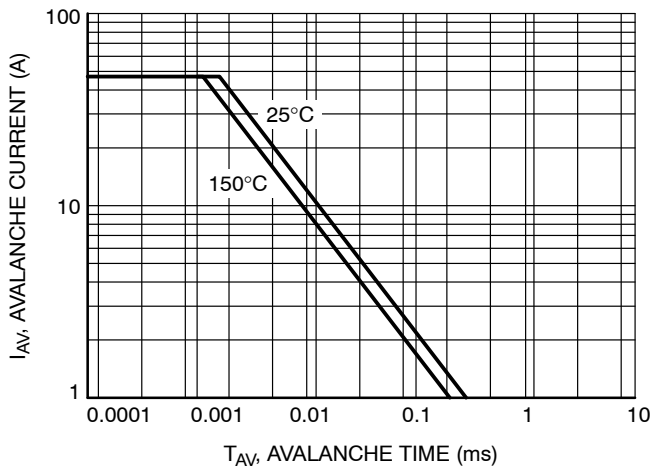


Figure 12. Unclamped Inductive Switching Capability

TYPICAL CHARACTERISTICS

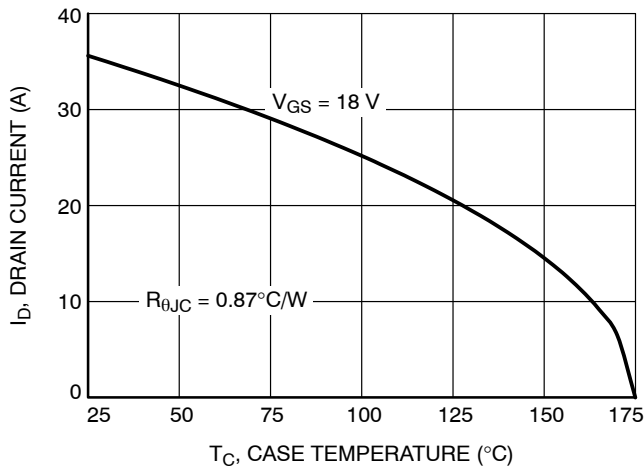


Figure 13. Maximum Continuous Drain Current vs. Case Temperature

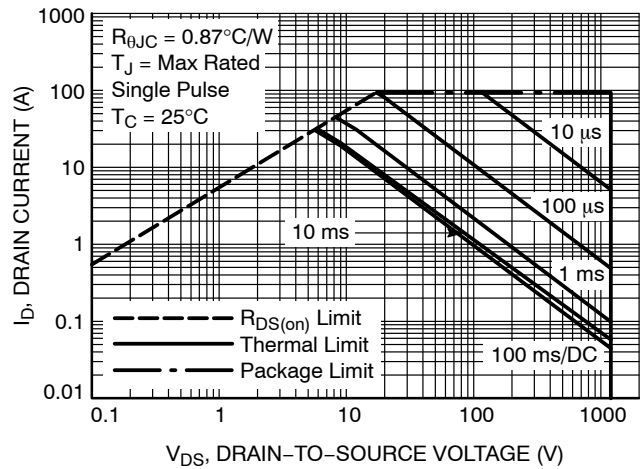


Figure 14. Safe Operating Area

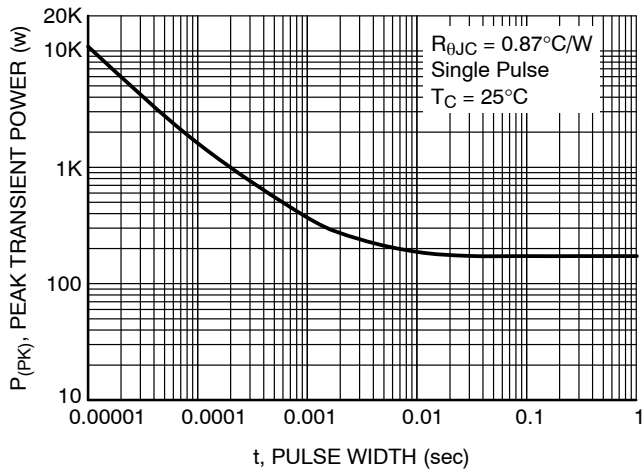


Figure 15. Single Pulse Maximum Power Dissipation

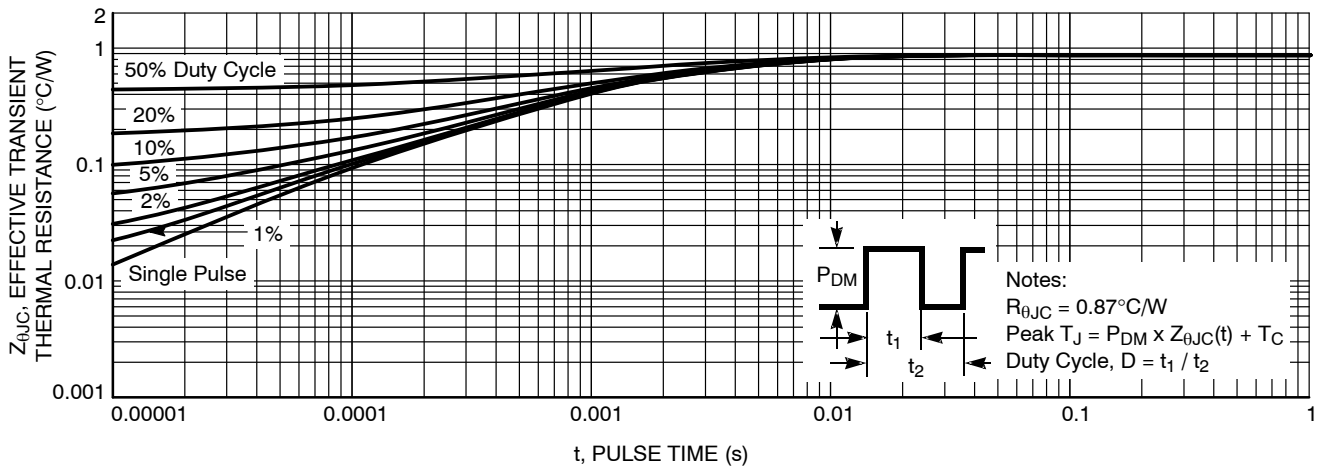
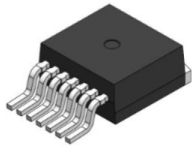
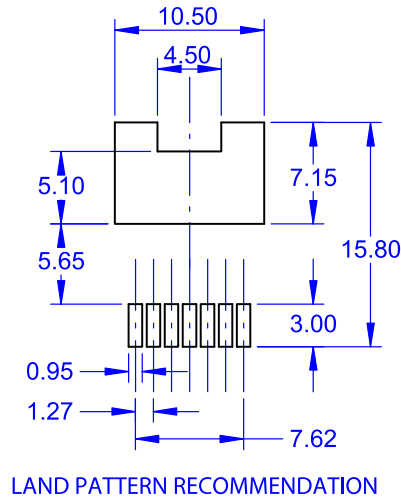
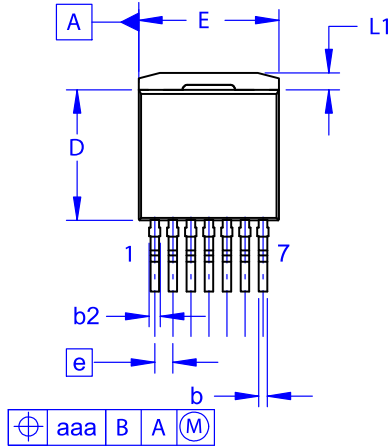


Figure 16. Junction-to-Case Transient Thermal Response



**D<sup>2</sup>PAK7 (TO-263-7L HV)**  
CASE 418BJ  
ISSUE B

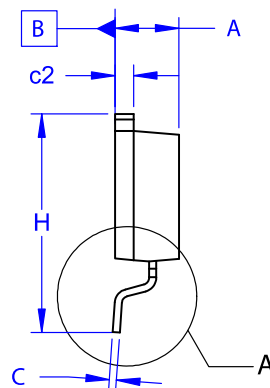
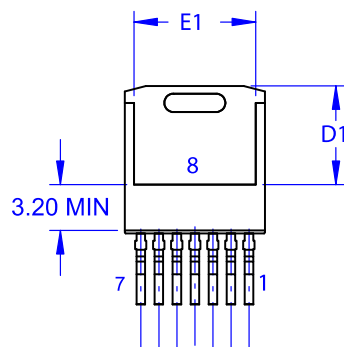
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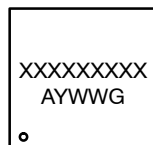
**NOTES:**

- A. PACKAGE CONFORMS TO JEDEC TO-263 VARIATION CB EXCEPT WHERE NOTED.
- B. ALL DIMENSIONS ARE IN MILLIMETERS.
- C. OUT OF JEDEC STANDARD VALUE.
- D. DIMENSION AND TOLERANCE AS PER ASME Y14.5-2009.
- E. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR PROTRUSIONS.

DIM	MILLIMETERS		
	MIN	NOM	MAX
A	4.30	4.50	4.70
A1	0.00	0.10	0.20
b2	0.60	0.70	0.80
b	0.51	0.60	0.70
c	0.40	0.50	0.60
c2	1.20	1.30	1.40
D	9.00	9.20	9.40
D1	6.15	6.80	7.15
E	9.70	9.90	10.20
E1	7.15	7.65	8.15
e	~	1.27	~
H	15.10	15.40	15.70
L	2.44	2.64	2.84
L1	1.00	1.20	1.40
L3	~	0.25	~
aaa	~	~	0.25

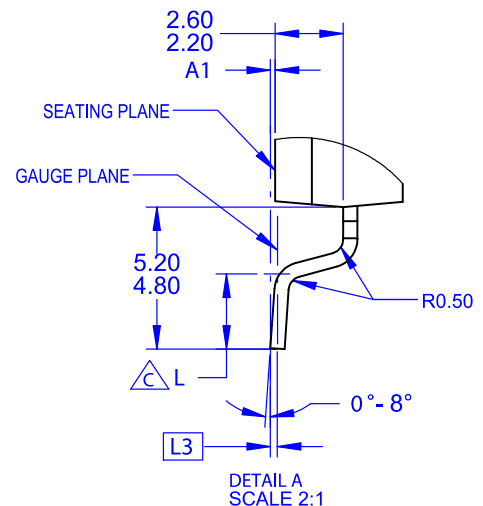


**GENERIC MARKING DIAGRAM\***



XXXX = Specific Device Code  
A = Assembly Location  
Y = Year  
WW = Work Week  
G = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.



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